

A-GT10

Strong Bonding Graphene Based Thermal Interface Material and Heatspreader

Features:

- Easy to use
- Strong bonding

Applications:

IGBT, GPU, CPU, LED, RF, Opto and power module cooling

Order status: small amount available now (□ 500pieces)

Description:

A-GT10 has curable polymer surface which can form strong bonding with different substrate surfaces. With a flexible structure, A-GT10 can easily fit and adhere to most all shapes and sizes of components to minimize the contact resistance and thereby leading to superior thermal performance. The bulk through-plane thermal conductivity of A-GT10 is orders of magnitude higher than conventional thermal interface materials. The effective thermal conductivity of A-GT10 is in the range of 10-12 W/mK. A-GT10 can be used for addressing large heat dissipation issues in electronics and other high power driven systems.

Properties	Value	Units	Test Method
Size	□ 4*4	cm ²	
Thickness	0.25-0.5 (± 15%)	mm	
Roughness	<5	%	
Color	Grey		
Filler Material	Graphene		
Density	0.5-0.8	g/cm ³	
Compressibility	20-30	%	ASTM
Recovery	15-20	%	ASTM
Compressive Strength	500	KPa	ASTM
Temperature Range	-40 to 200	°C	
Bulk Through-plane Thermal Conductivity	350-450	W/mK	LFA447
Effective Through-plane Thermal Conductivity	10-12	W/mK	ASTM
Thermal Resistance	50-60	Kmm ² /W	ASTM
Bulk In-plane (parallel to alignment) Thermal Conductivity	350-450	W/mK	LFA447
Bulk In-plane (perpendicular to alignment) Thermal Conductivity	1-2	W/mK	LFA447
Specific Heat	0.2-0.3	J/g.K	Hotdisk
Minimum shear strength	2.5	MPa	Dage 4000

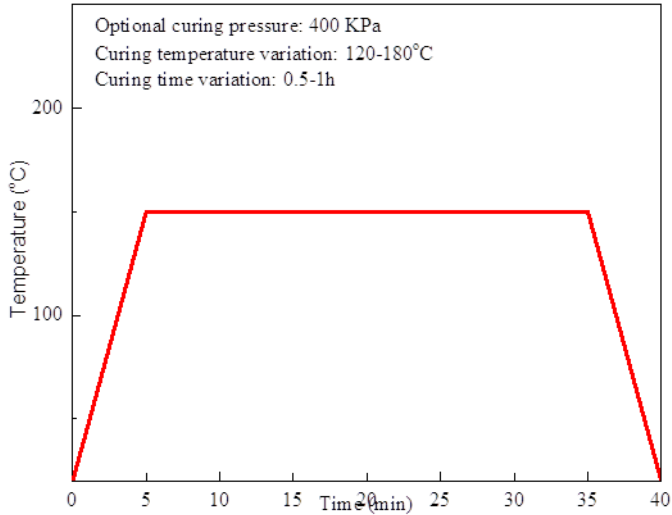
SHT Smart High Tech AB
Post address: Kemivägen 6, SE 412
58 Göteborg, Sweden



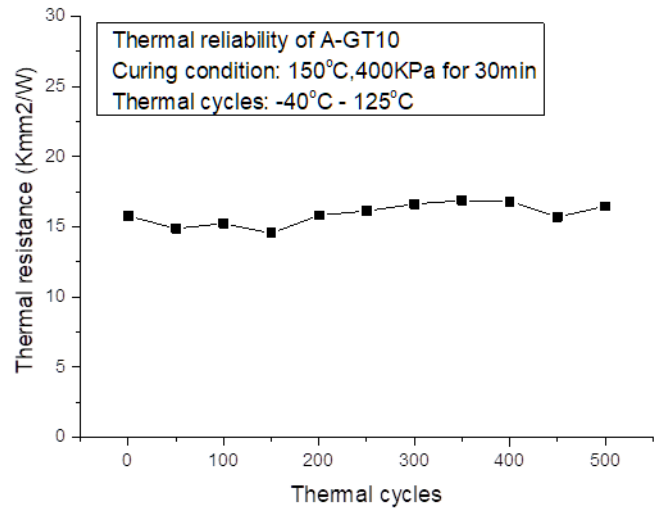
Phone: +46(0)76 948 99 96
Email: info@sht-tek.com

www.sht-tek.com

Temperature profile of curing A-GT10



Thermal reliability of A-GT10



Shear strength curve of A-GT10 at in-plane direction

